

Abstract of the Disclosure

A method and apparatus for dissipating heat from an electronic device is described. The method and apparatus provides a scalable, cost effective, highly efficient, universally applied thermal solution for high heat generating electronic components. In one embodiment, a housing attaches over a heat sink for an electronic device. Various cooling attachments can be attached to this housing to provide a multitude of air flow enhancers. The cooling attachments are designed to provide a thermal engineer or a system integrator with several options for cooling an electronic component. The cooling attachments can be placed in multiple configurations to provide unique thermal solutions. In another embodiment, a kit of parts for a cooling system is provided. The kit of parts includes a housing and a variety of cooling attachments.

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